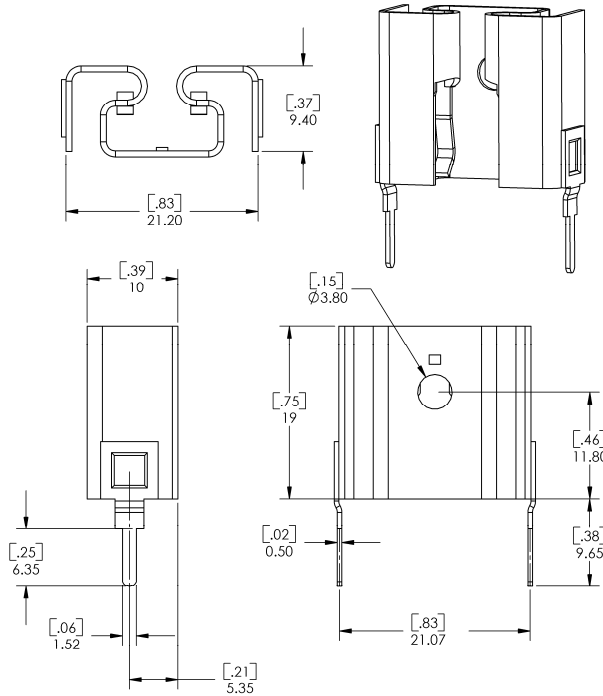


Board Level Heat Sinks



ThermaFlo

P/N: 833202B03700



PRODUCT SPECIFICATIONS

- Devices: TO-220
- Size: 10.0 x 21.2 x 19.0 mm
- Material: Aluminum, 0.8 mm Thick
- Type: Stamped
- IC Mounting: Integrated Spring
- PCB Mounting: Solderable Step Tabs
- Finish: Black Anodized
- Package: Bulk

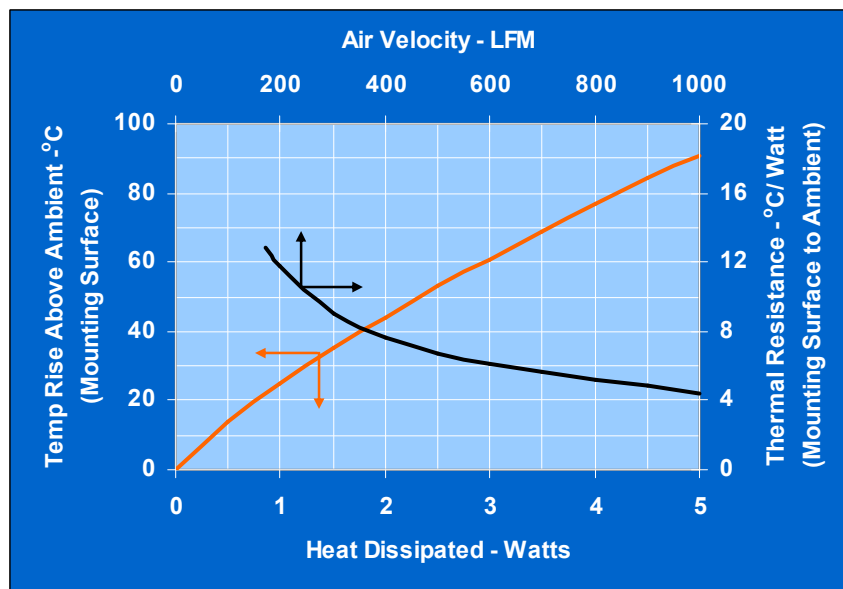
FEATURES & BENEFITS

- No Hardware Device Attachment
- Constant Spring Force Tension
- Vertical Mounting via Solderable Tabs
- RoHS Compliant



CUSTOMIZED HEATSINKS

- Specialized Tabs, Plating
- Specialized Body Configurations
- Contact Applications Engineering



TO-220

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